

Cree® EZ400™ LED

Data Sheet

CxxxEZ400-Sxxx00

Cree's EZBright™ LEDs are the next generation of solid-state LED emitters that combine highly efficient InGaN materials with Cree's proprietary optical design and device technology to deliver superior value for high-intensity LEDs. The optical design maximizes light extraction efficiency and enables a Lambertian radiation pattern. Additionally, these LEDs are die attachable with conductive epoxy, solder paste or solder preforms, as well as the flux eutectic method. These vertically structured, low forward voltage LED chips are approximately 100 microns in height. Cree's EZ™ chips are tested for conformity to optical and electrical specifications. These LEDs are useful in a broad range of applications, such as general illumination, automotive lighting and LCD backlighting.

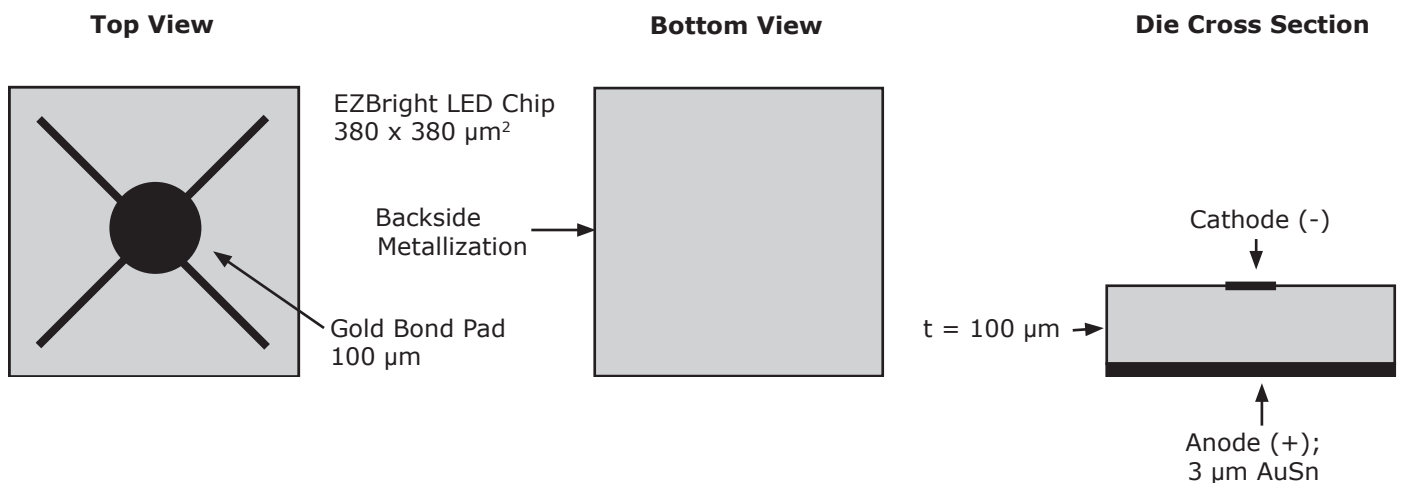
FEATURES

- EZBright Power Chip LED Rf Performance
 - 60 mW min. @ 150 mA – 450 & 460 nm
 - 25 mW min. @ 150 mA - 527 nm
- Lambertian Radiation
- Conductive Epoxy, Solder Paste or Preforms, or Flux Eutectic Attach
- Thin 100- μ m Chip
- Low Forward Voltage – 3.5 V Typical at 150 mA
- Single Wire Bond Structure
- Maximum DC Forward Current - 200 mA

APPLICATIONS

- General Illumination
 - Automobile
 - Aircraft
 - Decorative Lighting
 - Task Lighting
 - Outdoor Illumination
- White LEDs
- Crosswalk Signals
- Television Backlighting

CxxxEZ400-Sxxx00 Chip Diagram



Maximum Ratings at $T_A = 25^\circ\text{C}$ ^{Note 1}		CxxxEZ400-Sxxx00
DC Forward Current		200 mA
Peak Forward Current		350 mA ^{Note 3}
LED Junction Temperature		145°C
Reverse Voltage		5 V
Operating Temperature Range		-40°C to +100°C
Storage Temperature Range		-40°C to +120°C

Typical Electrical/Optical Characteristics at $T_A = 25^\circ\text{C}$, $I_f = 150\text{ mA}$ ^{Note 2}					
Part Number	Forward Voltage (V_f , V)			Reverse Current [$I(V_r=5\text{ V})$, μA]	Full Width Half Max (λ_D , nm)
	Min.	Typ.	Max.	Max.	Typ.
C450EZ400-Sxxx00	3.1	3.5	4.1	2	21
C460EZ400-Sxxx00	3.1	3.5	4.1	2	21
C527EZ400-Sxxx00	3.1	3.7	4.1	2	35

Mechanical Specifications			CxxxEZ400-Sxxx00
Description	Dimension	Tolerance	
P-N Junction Area (μm)	350 x 350	± 40	
Chip Area (μm)	380 x 380	± 40	
Chip Thickness (μm)	100	± 25	
Top Au Bond Pad Diameter (μm)	100	± 15	
Au Bond Pad Thickness (μm)	3.0	± 1.0	
Back Contact Metal Area (μm)	380 x 380	± 40	
Back Contact Metal Thickness (μm)	3.0	± 1.0	

Notes:

1. Maximum ratings are package-dependent. The above ratings were determined using a Au-plated TO39 header without an encapsulant for characterization. Ratings for other packages may differ. The junction temperature should be characterized in a specific package to determine limitations. Assembly processing temperature must not exceed 325°C (< 5 seconds). See Cree EZBright Applications Note for assembly-process information.
2. All products conform to the listed minimum and maximum specifications for electrical and optical characteristics when assembled and operated at 150 mA within the maximum ratings shown above. Efficiency decreases at higher currents. Typical values given are within the range of average expected by the manufacturer in large quantities and are provided for information only. All measurements were made using a Au-plated TO39 header without an encapsulant. Optical characteristics measured in an integrating sphere using Illuminance E.
3. This peak forward current specification is based on a 400-ms pulse width at a 1/5-duty cycle with a junction temperature of 65°C.

Standard Bins for CxxxEZ400-Sxxx00

LED chips are sorted to the **radiant flux** and **dominant wavelength** bins shown. A sorted die sheet contains die from only one bin. Sorted die kit (CxxxEZ400-Sxxx00) orders may be filled with any or all bins (CxxxEZ400-0xxx) contained in the kit. All radiant flux and all dominant wavelength values shown and specified are at $I_f = 150$ mA. Radiant flux values are measured using Au-plated TO39 headers without an encapsulant.

C450EZ400-S06000

Radiant Flux	105 mW	C450EZ400-0213	C450EZ400-0214	C450EZ400-0215	C450EZ400-0216	
	90 mW	C450EZ400-0209	C450EZ400-0210	C450EZ400-0211	C450EZ400-0212	
	75 mW	C450EZ400-0205	C450EZ400-0206	C450EZ400-0207	C450EZ400-0208	
	60 mW	C450EZ400-0201	C450EZ400-0202	C450EZ400-0203	C450EZ400-0204	
		445 nm	447.5 nm	450 nm	452.5 nm	455 nm
Dominant Wavelength						

C460EZ400-S06000

Radiant Flux	105 mW	C460EZ400-0213	C460EZ400-0214	C460EZ400-0215	C460EZ400-0216	
	90 mW	C460EZ400-0209	C460EZ400-0210	C460EZ400-0211	C460EZ400-0212	
	75 mW	C460EZ400-0205	C460EZ400-0206	C460EZ400-0207	C460EZ400-0208	
	60 mW	C460EZ400-0201	C460EZ400-0202	C460EZ400-0203	C460EZ400-0204	
		455 nm	457.5 nm	460 nm	462.5 nm	465 nm
Dominant Wavelength						

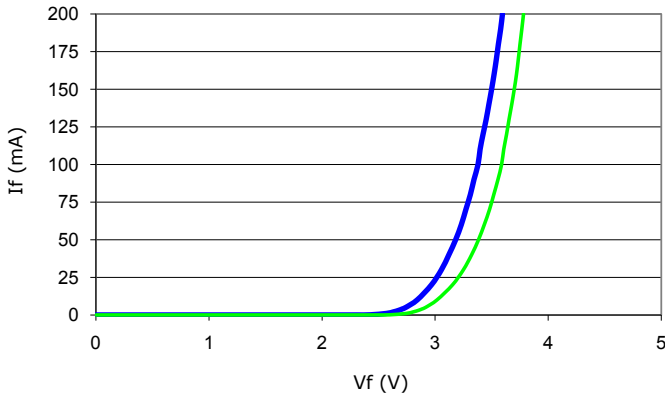
C527EZ400-S02500

Radiant Flux	35 mW	C527EZ400-0204	C527EZ400-0205	C527EZ400-0206	
	25 mW	C527EZ400-0201	C527EZ400-0202	C527EZ400-0203	
		520 nm	525 nm	530 nm	535 nm
Dominant Wavelength					

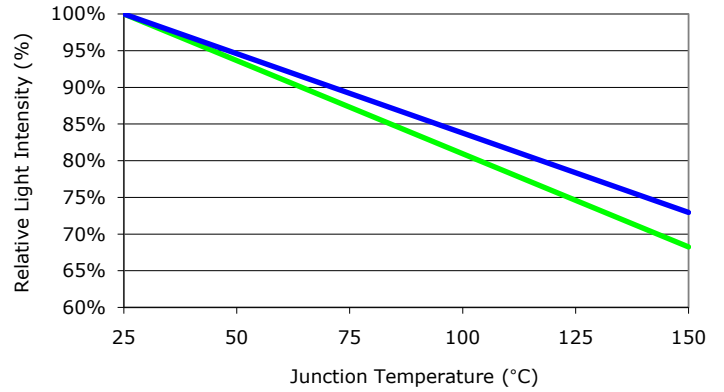
Characteristic Curves

These are representative measurements for the EZBright400. Actual curves will vary slightly for the various radiant flux and dominant wavelength bins.

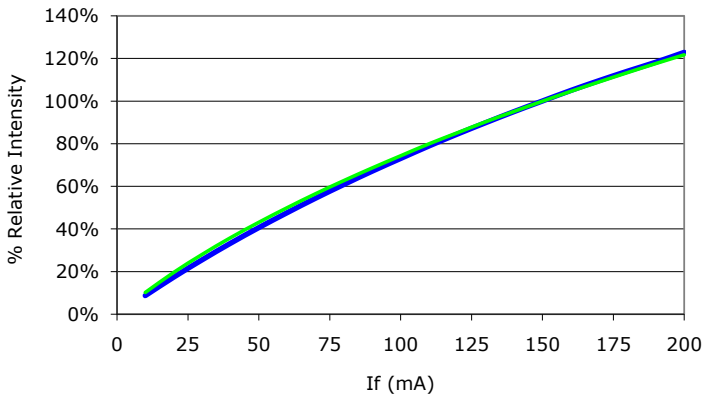
Forward Current vs. Forward Voltage



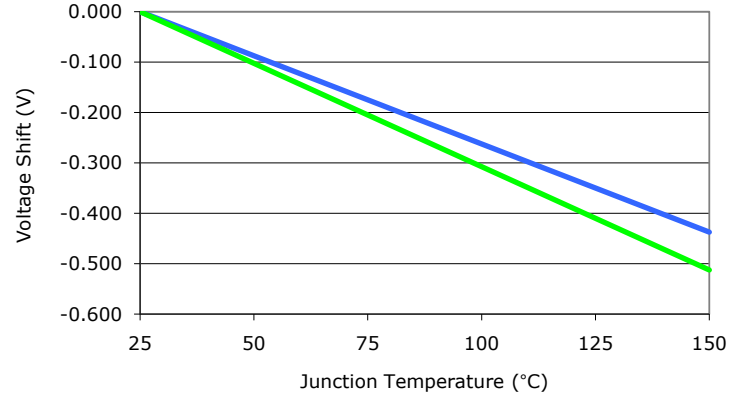
Relative Light Intensity Vs Junction Temperature



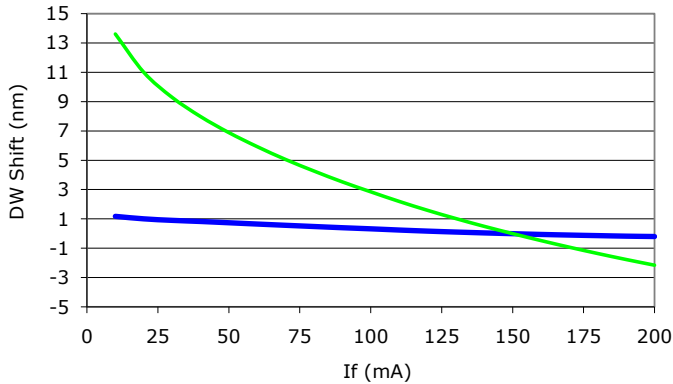
Relative Intensity vs. Forward Current



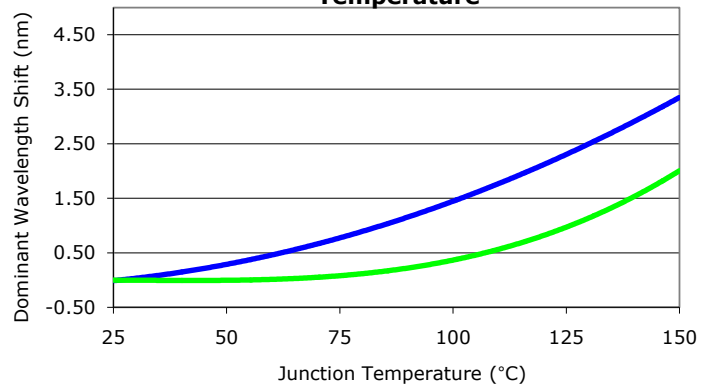
Voltage Shift Vs Junction Temperature



Dominant Wavelength vs. Forward Current



Dominant Wavelength Shift Vs Junction Temperature



Radiation Pattern

This is a representative radiation pattern for the EZBright Power Chip LED product. Actual patterns will vary slightly for each chip.

